



Title of Change:	Qualification of ON Semiconductor Mountain Top, USA facility as an additional wafer fab location for MV5 Technology.	
Proposed first ship date:	29 June 2018	
Contact information:	Contact your local ON Semiconductor Sales Office or <yuna.im@onsemi.com>.	
Samples:	Contact your local ON Semiconductor Sales Office	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <youngchul.lee@onsemi.com>.	
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.	
Change Part Identification:	Affected parts will be identified with a date code of WW07'18 or later	
Change category:	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: ON Mountain Top, PA	External Foundry/Subcon Sites: None
Description and Purpose:		
<p>This is a Final Change Notification to inform customers of the qualification of ON Semiconductor Mountain Top, USA facility as an additional wafer fab location for MV5 Technology.</p> <p>At the expiration of this notification, all products listed here will be dual sourced from its current ON Semiconductor wafer fab in Bucheon, Korea.</p>		
	Before Change Description	After Change Description
Fab site	ON Semiconductor Bucheon, Korea	ON Semiconductor Bucheon, Korea ON Semiconductor Mountain Top, PA



Reliability Data Summary:

DEVICE NAME: FDB075N15A

PACKAGE: TO-263

Test	Specification	Condition	Interval	Results
PC	JEDS22 A113	Performed prior to TC, UHAST, HAST and IOL.		0/924
EV	JEDS22 B101	Device construction, marking, and workmanship		0/All
PV	Device specification	Tested to device specification requirements		0/45
HTRB	MILSTD750-1 method M1038A	Tj= 175C, bias= 120V, 1000 hrs	1000 hrs	0/231
HTGB	JESD22 A108	Ta= 175C, bias= 20V, 1000 hrs	1000 hrs	0/231
TC	JESD22 A104; Q101 appendix 6	T air= -65C to 150C, t dwell > 15 min, 500 cycles	500 cycles	0/231
UHAST	JESD22 A118	Ta= 130C, RH= 85%, no bias, 96 hrs	96 hrs	0/231
HAST	JESD22 A110	Ta= 130C, RH= 85%, bias= 42V, 96 hrs	96 hrs	0/231
IOL	MIL-STD-750 Method 1037	Ta=25C, delta Tj=100C, ton=toff=3.5min, 8572 cycles	8572 cycles	0/231
ESD	AEC Q101-001/005	Prefer CDM and HBM.		0/6
DPA	AEC Q101-004 Section 4	Post H3TRB or HAST and TC		0/39
RSH	JESD22 B106	Per AEC - Q101		0/30
WBS	MIL-STD-750 Method 2037	Pre & post process change		0/66
BS	AEC Q101-003			0/66
DS	MIL-STD-750 Method 2017			0/66
UIS	AEC Q101-004 Section 2			0/72

DEVICE NAME : FDC86244

PACKAGE: TSOT-23

Test	Specification	Condition	Interval	Results
PC	JEDS22 A113	Performed prior to TC, UHAST, HAST and IOL.		0/327
EV	JEDS22 B101	Device construction, marking, and workmanship		0/All
PV	Device specification	Tested to device specification requirements		0/15
HTRB	MILSTD750-1 method M1038A	Tj=150C, bias= 120V	1008 hrs	0/80
HTGB	JESD22 A108	Ta=150C, bias=20V	1008 hrs	0/80
HTSL	JESD22 A108	Ta=150C	1008 hrs	0/90
TC	JESD22 A104; Q101 appendix 6	T air= -65C to 150C, t dwell > 15 min	1000 cycles	0/85
UHAST	JESD22 A118	Ta=130C, RH=85%, no bias	96 hrs	0/82
HAST	JESD22 A110	Ta=130C, RH=85%, bias=42V	96 hrs	0/80
IOL	MIL-STD-750 Method 1037	Ta=25C, delta Tj=100C, ton=toff=2min	15000 cycles	0/80
ESD (HBM)	AEC Q101-001	HBM		0/3 (300V)
ESD (CDM)	AEC-Q101-005	CDM		0/3 (2000V)
DPA	AEC Q101-004 Section 4	Post TC		0/2
RSH	JESD22 B106	Per AEC - Q101		0/30
WBS	MIL-STD-750 Method 2037	Pre & post process change		0/30
BS	AEC Q101-003			0/30
UIS	AEC Q101-004 Section 2			0/24

**Electrical Characteristic Summary:**

Electrical characteristics are not impacted.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
FDB082N15A	FDB075N15A
FDP083N15A-F102	FDB075N15A
FDPF770N15A	FDB075N15A
FDB110N15A	FDB075N15A
FDH055N15A	FDB075N15A
FDI045N10A-F102	FDB075N15A
FDP045N10A-F102	FDB075N15A
FDPF045N10A	FDB075N15A
FDP085N10A-F102	FDB075N15A
FDPF085N10A	FDB075N15A
FDC86244	FDC86244
FDMC86244	FDC86244
FDT86244	FDC86244